



# EXPERT 10.6 RS

## 5,300 W Rework station

Semi-automated rework station with Gantry system for small to very large and massive components. The proven hybrid underheater allows gentle heating of boards with dimensions up to 500x500 mm<sup>2</sup>. For safe handling of all components, the precise positioning

system can navigate to any point on the PCB. Pre-positioning is performed via the smooth-running XY gantry, while fine positioning and placement is fully automatic using reliable Martin precision/-technology.

### Top Features

Camera-supported rework



#### Flexibility

Good accessibility of all components on the board via the gantry system & compact footprint at the same time



#### Under-heating system

Large PCBs 500 x 500 mm<sup>2</sup>



#### Performance

High cycle time due to easy prepositioning of the arm via gantry system



#### Multifunctionality

One device for all processes, including desoldering, pad cleaning, automatic positioning and soldering



#### Process control

Automatic profiler for under- and top-heating systems



#### Software

Simple, intuitive, tablet-compatible

### Standard equipment

- Set of placement nozzles XL-type (BGA/CSP) 5 mm, 8 mm, 15 mm with O-Ring
- Set of solder nozzles (BGA) 15 mm, 27 mm, 35 mm, 40 mm
- Two camera lenses (BGA, CSP)
- Two thermocouple sensors (type K)
- Four PCB magnet holder 40.5 mm (standard)
- Two PCB clips to install at hand rest
- Manual
- Intuitive software EASYSOLDER 07 with touch integration


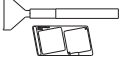
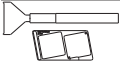
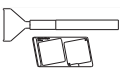

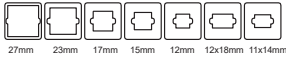

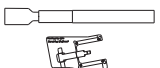


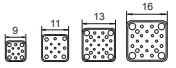
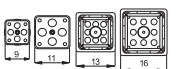
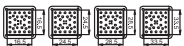
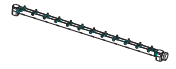
### Technical details

<b>Power consumption:</b>	5500 VA	
<b>Power solder pen:</b>	400 W, 35 l/min	
<b>Power under-heating system:</b>	1200 - 5000 W	8 x IR-lamps
<b>Size under-heating system:</b>	450 x 420 mm <sup>2</sup>	
<b>Max. PCB size:</b>	500 x 500 mm <sup>2</sup>	
<b>Resolution motion system:</b>	0.001 mm	
<b>Placement accuracy:</b>	± 0.015 mm	(Flip Chip)*
	± 0.030 mm	(CSP)
	± 0.040 mm	(BGA)
	± 0.070 mm	(Maxi BGA)*
	± 0.115 mm	(Maxi BGA XL)*

<b>High resolution CMOS-camera:</b>	5 Mio. Pixel USB2	
<b>Camera field of view (FOV):</b>	16 x 22 mm <sup>2</sup>	(Flip Chip)*
	32 x 42 mm <sup>2</sup>	(CSP)
	42 x 57 mm <sup>2</sup>	(BGA)
	71 x 96 mm <sup>2</sup>	(Maxi BGA)*
	115 x 160 mm <sup>2</sup>	(Maxi BGA XL)*
<b>Mains:</b>	1Phase, 230VAC, Fuse 25A	
	Connector Type CEE 32A (3 phase)	
<b>Pressurized air:</b>	5-8 bar, 100 l/min	clean, dry air
<b>Dimensions:</b>	1030 x 630 mm <sup>2</sup>	

\* Optional extras

## EXPERT 10.6 RS: Optional extras

	Article nr.	Name
	SF66.0501	Tool Shuttle 40 for AVP 4.1XL
	SF64.0525	Dip Tool 0.08mm with squeegee for tool shuttle 32 / 40
	SF64.0526	Dip Tool 0.15mm with squeegee for tool shuttle 32 / 40
	SF64.0527	Dip Tool 0.22mm with squeegee for tool shuttle 32 / 40
	SF66.0526	Dip Tool 0.15mm with squeegee for tool shuttle 40 only
	AT10.0100	Chip Frame Set Dip Tool 7 / 32*32mm 7 pcs (11*14, 12*18, 12, 15, 17, 23, 27)
	AT20.0100	Chip Frame Set Dip Tool 7 / 40*40mm 7 pcs (15, 17, 23, 27, 31, 35, 37.5)
	SF64.0520	Print Tool with squeegee for tool shuttle 32 / 40
	DB00.0025	Nitrogen input for DBL 04/05/06 (2.p.r) reduces consumption of N2 for vacuum
	SF66.0110	Lens Maxi BGA for AVP4/4XL, f=16mm, 65*85mm
	LW40.1096	Soldering nozzle set CSP/QFN 4 for all CSP types, 4 pieces (9, 11, 13, 16)
	LW40.1104	Soldering nozzle set CSP with vacuum 4 for all CSP types, 4 pieces (9, 11, 13, 16)
	LW40.1099	Solder Nozzle Set BGA 7 7 pieces (15, 23, 27, 31, 35, 37.5, 40)
	SF36.1002	PCB flex support h=40.5 mm for HIF 09, "12 pin"

Additional accessories and consumables are available on [www.martin-smt.de/en/shop/](http://www.martin-smt.de/en/shop/)